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(12) **United States Design Patent**
Morelli et al.

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- (54) **CONNECTION MODULE**
- (71) Applicant: **Telit Communications S.p.A.**, Sgonico (Trieste) (IT)
- (72) Inventors: **Andrea Morelli**, Cagliari (IT); **Antonino Sgroi**, Trieste (IT); **Bruno Vittori**, Sagrado (IT); **Carlo Antonini**, Trieste (IT); **Claudio Deltin**, Grado (IT)
- (73) Assignee: **Telit Communications S.p.A.**, Sgonico (Trieste) (IT)
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- (51) **LOC (12) Cl.** **13-03**
- (52) **U.S. Cl.**
USPC **D13/147**
- (58) **Field of Classification Search**
USPC D13/120, 121, 182, 184, 199, 133, 147, D13/154; D14/230, 240
CPC H01R 9/00; H01R 12/00; H01R 13/00; H01R 24/00; H01R 33/00; H05K 2201/10287; H05K 2201/1031; H05K 2201/10659; H05K 2201/10689; H05K 2201/10719; H05K 2201/1084; H05K 3/222; H05K 1/00; H05K 1/0213; H05K 1/0215; H05K 1/182; Y10T 29/00; Y10T 29/49147; Y10T 29/49149; Y10T 29/49155; Y10T 29/49156
See application file for complete search history.

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Primary Examiner — Elizabeth J Oswecki
(74) *Attorney, Agent, or Firm* — Pearl Cohen Zedek Latzer Baratz LLP

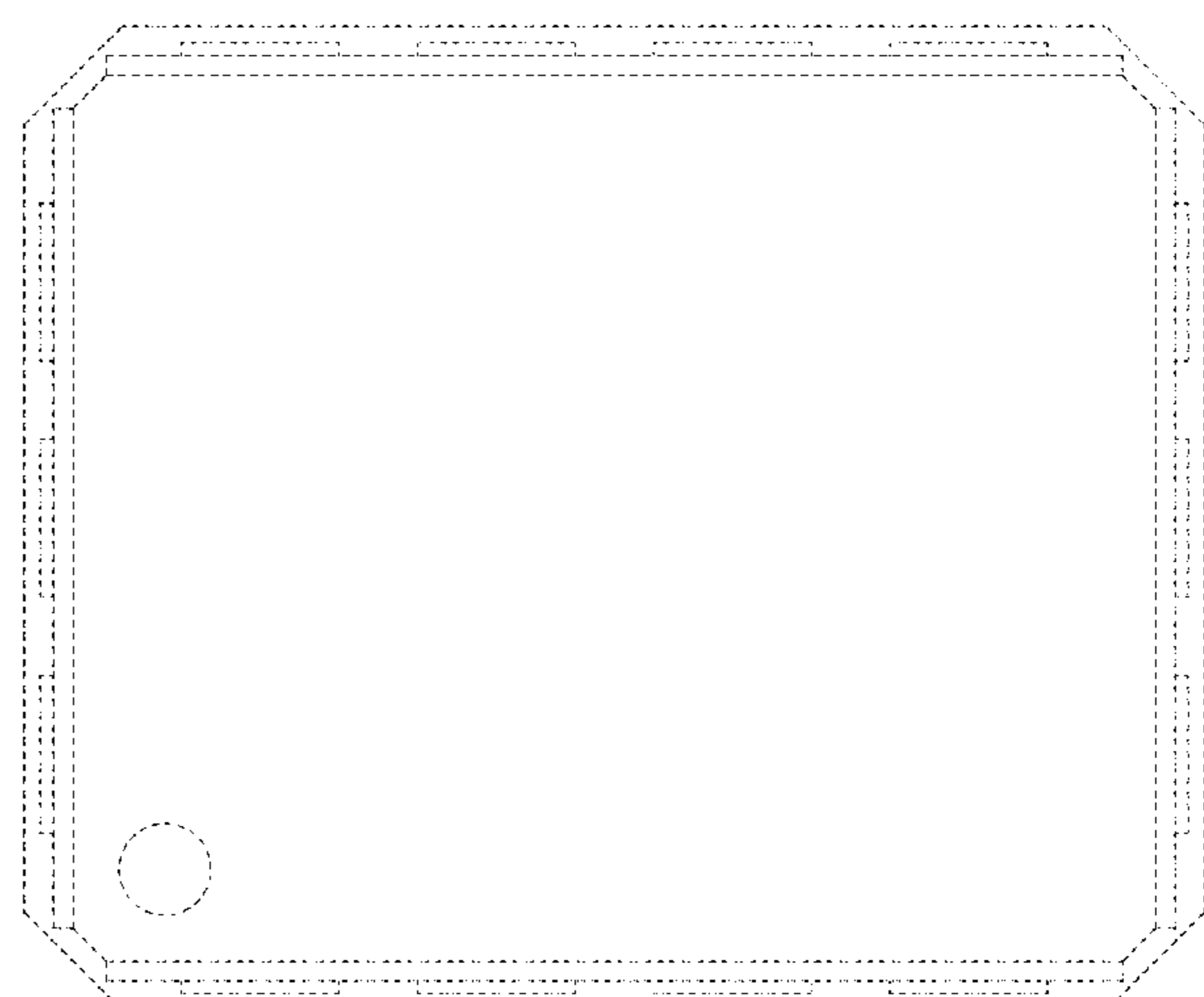
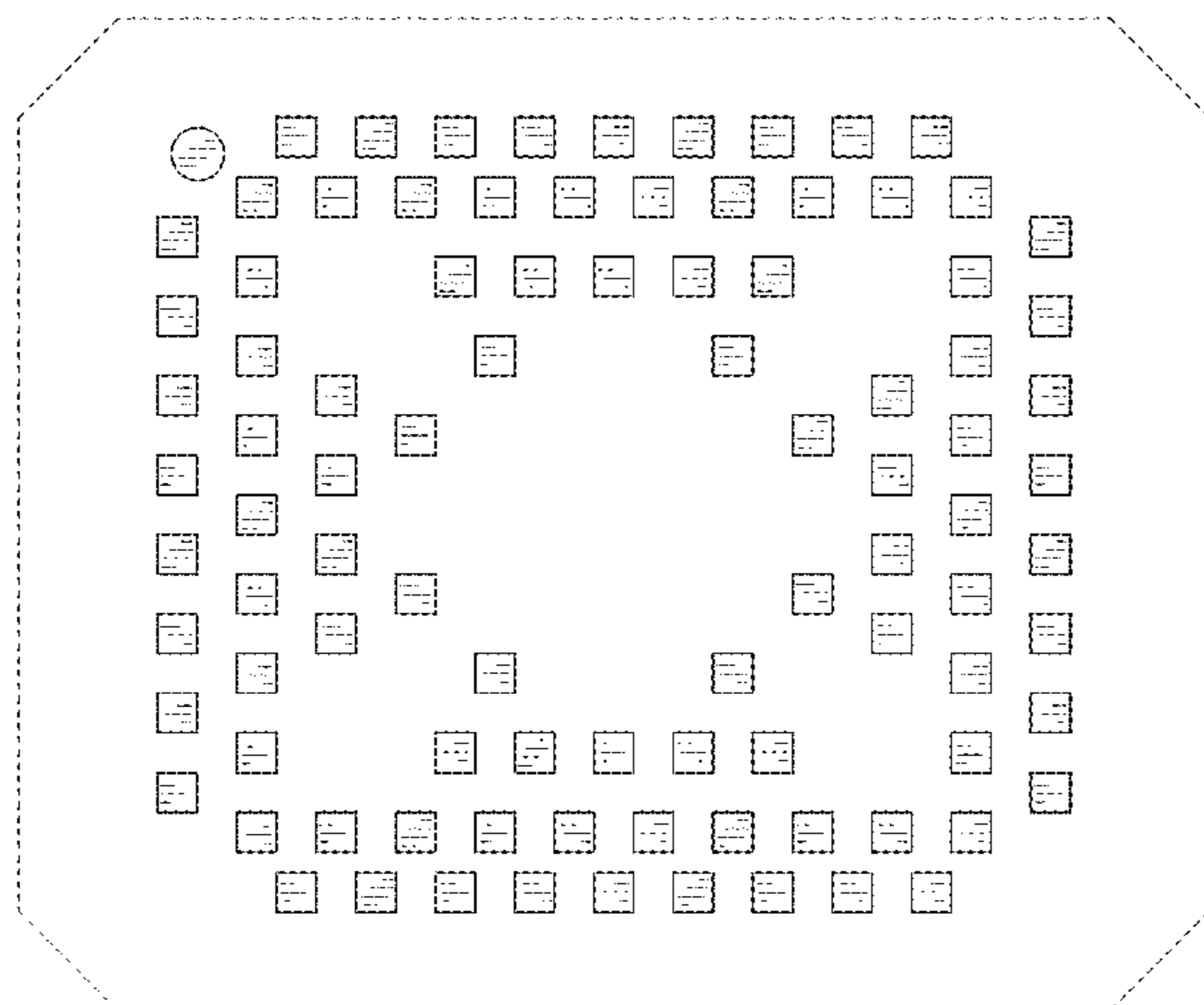
(57) **CLAIM**

The ornamental design for a connection module, as shown and described.

DESCRIPTION

FIG. 1 is a top, front, right side perspective view of a connection module showing our new design;
FIG. 2 is a bottom plan view thereof;
FIG. 3 is a top plan view thereof;
FIG. 4 is a right side elevation view thereof;
FIG. 5 is a left side elevation view thereof;
FIG. 6 is a back elevation view thereof;
FIG. 7 is a front elevation view thereof; and,
FIG. 8 is a bottom, back, left side perspective thereof.
The broken lines show portions of the connection module that form no part of the claimed design.

1 Claim, 5 Drawing Sheets



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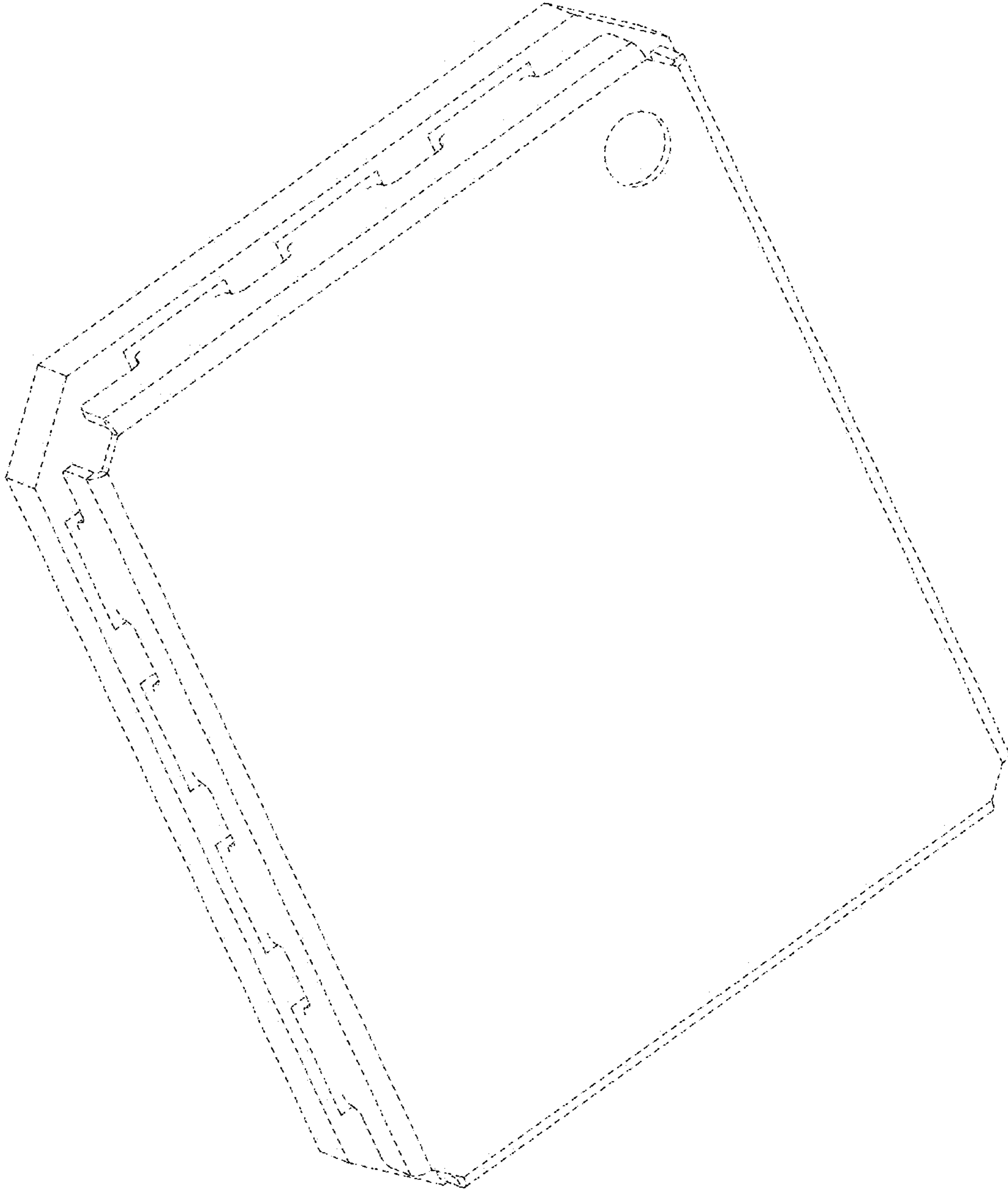


FIG. 1

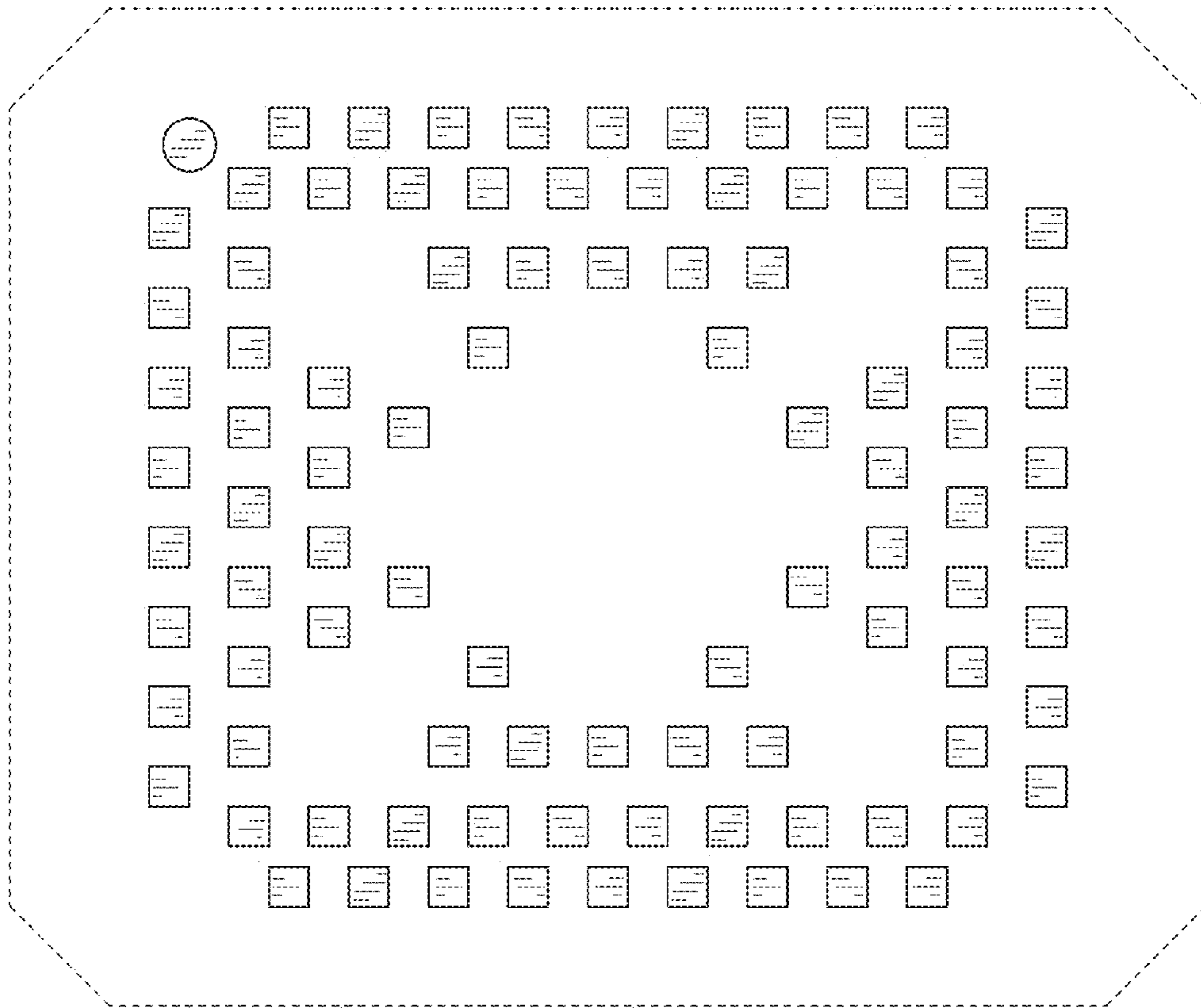


FIG. 2

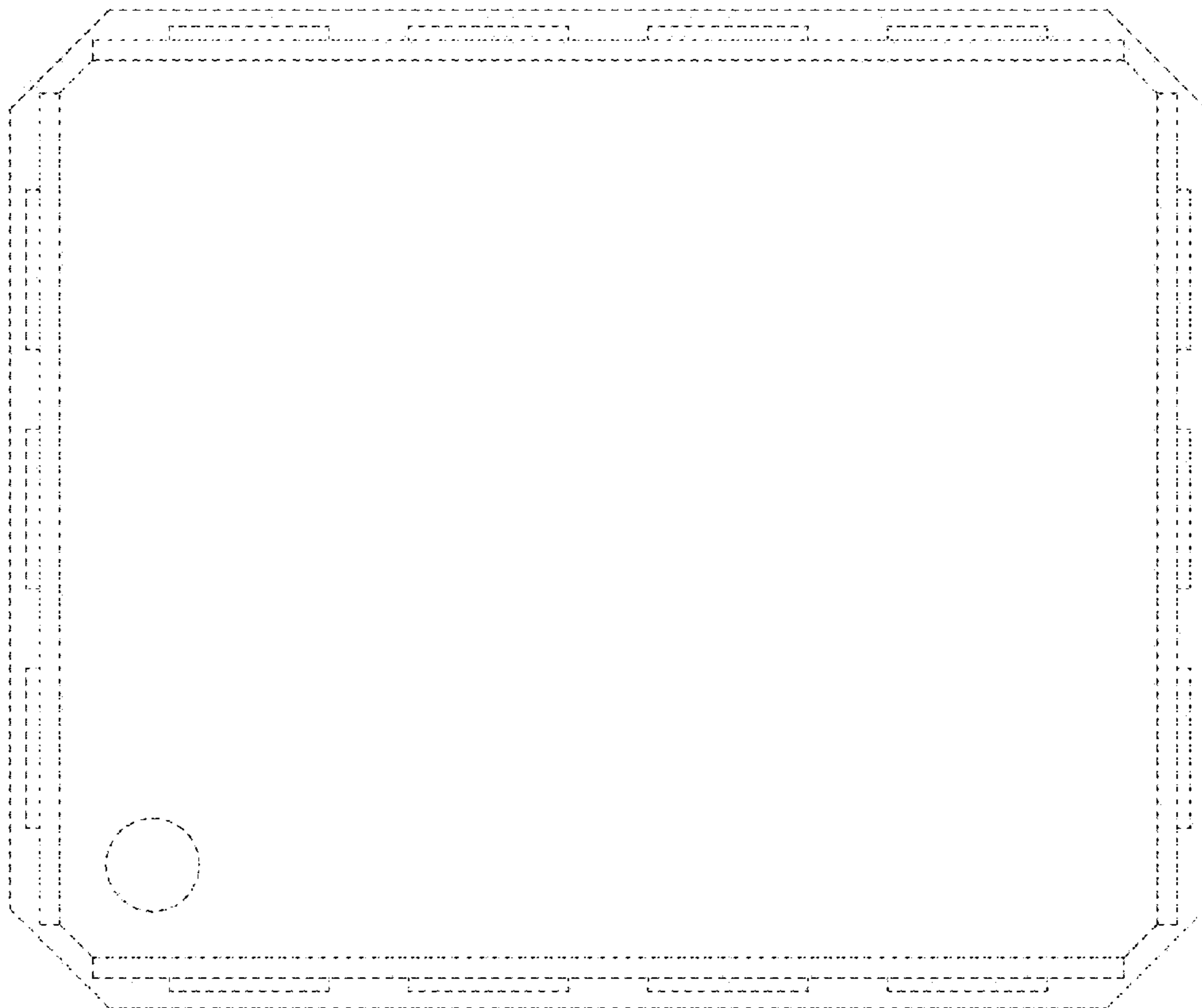


FIG. 3

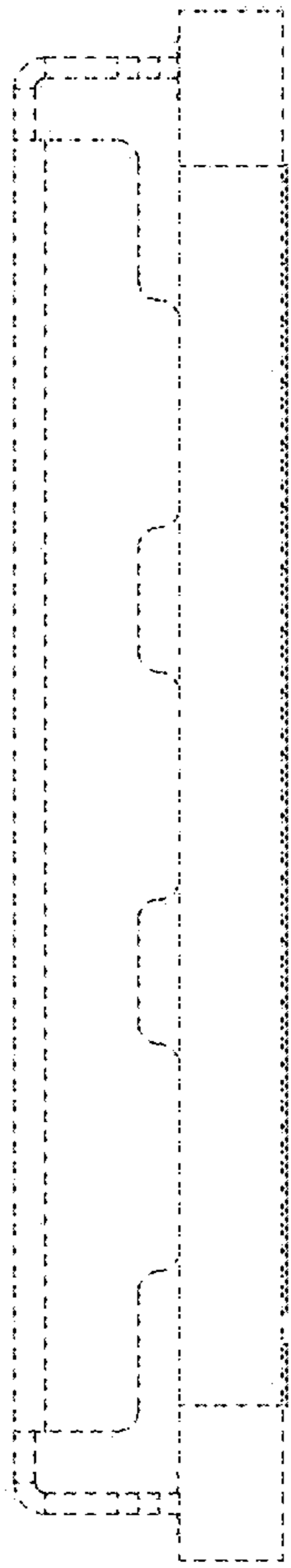


FIG. 4

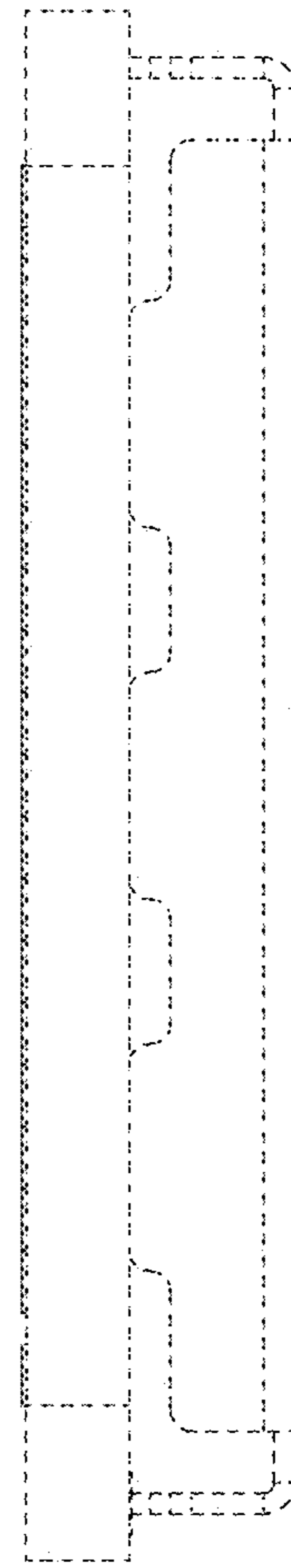


FIG. 5

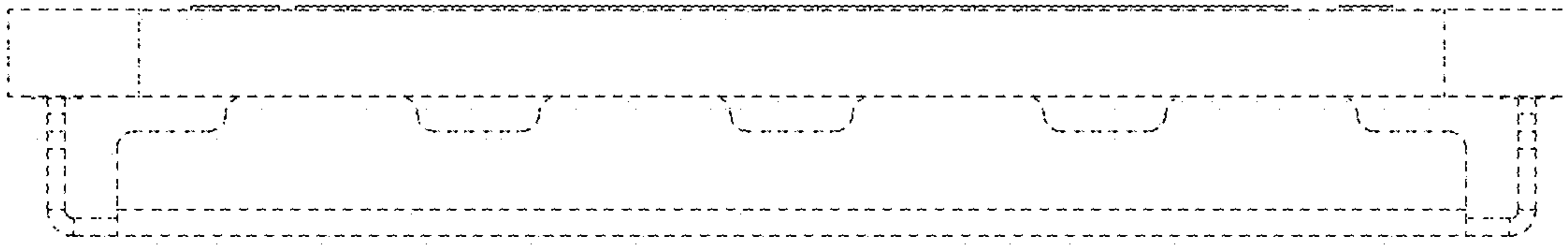


FIG. 6

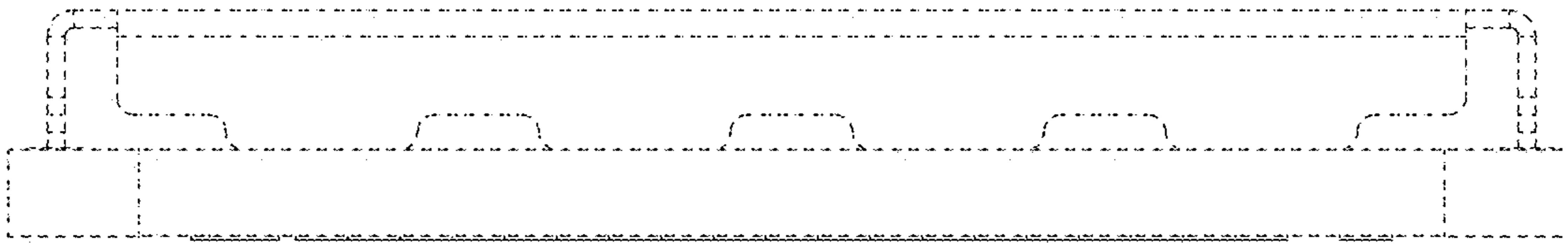


FIG. 7

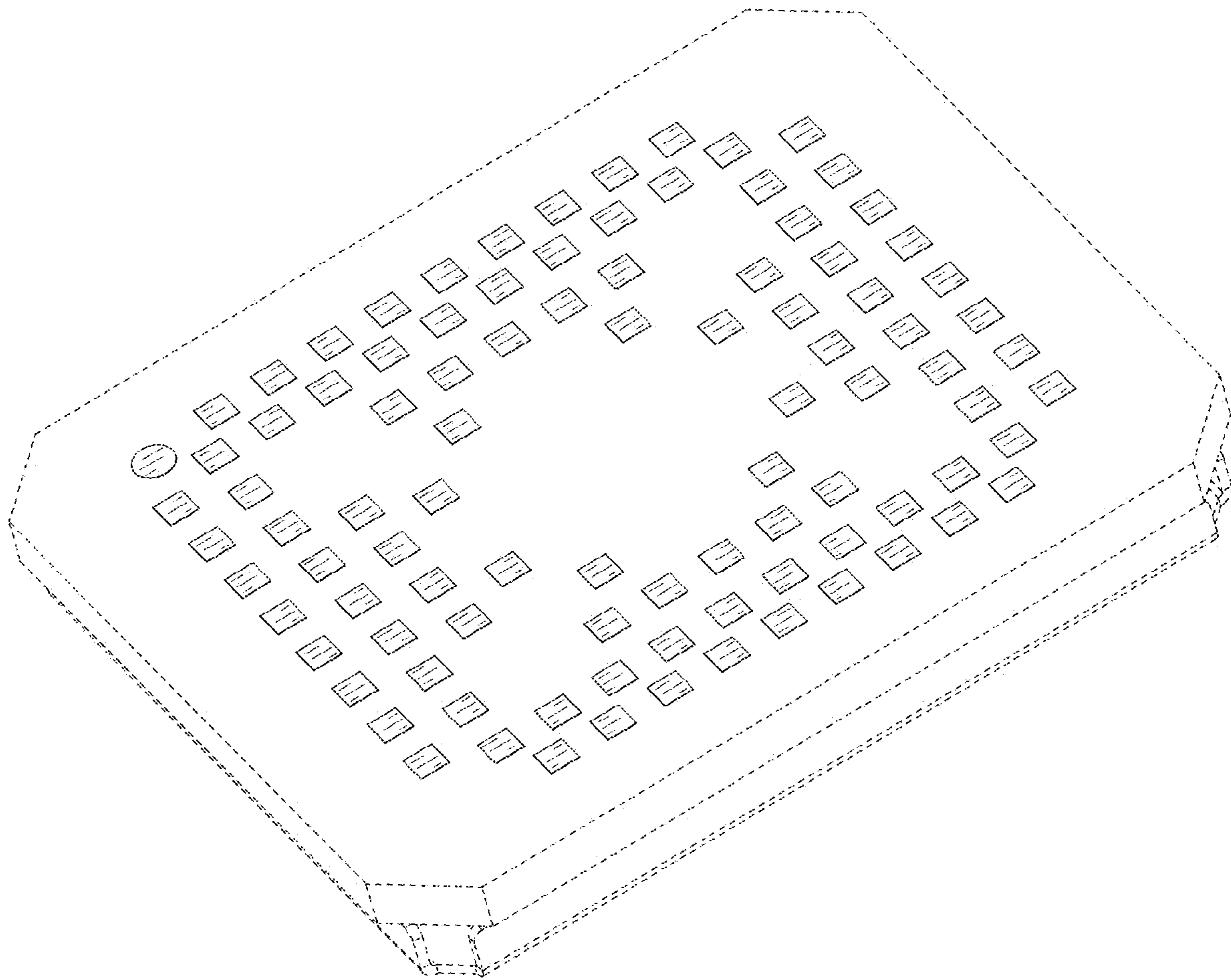


FIG. 8